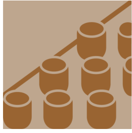
materials

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Novel Materials and Processes for Electronic Packaging

Guest Editor:

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Deadline for manuscript submissions:
closed (10 December 2022)

Message from the Guest Editor

Dear Colleagues,

Driven by new applications ranging from super-computing and fifth/sixth-generation (5G/6G) communications to electric vehicles (EVs) and green energy, advanced high-density electronic packaging technologies, as well as high-power electronic interconnection are in great demand in the electronic industry. Meanwhile, sustainable materials and manufacturing technologies are also needed to meet the low-emission requirements for carbon neutrality. To achieve high-density and high-reliable electronic devices with low energy consumption, innovative materials and processes for electronic packaging play key roles. For high-density packaging, three-dimensional (3D) integration is an emerging technology, while for sustainable processes, low-temperature processes are desired. The 3D structures involve through-silicon-via (TSV), advanced ceramic substrates, and metal-to-metal or metal-to-ceramics bonding, which require various kinds of electronic interconnection technologies.

Research papers and critical reviews on these fields are both highly welcome.

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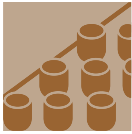
Special Issue



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